

Special Issue

Thermal Interface Materials: Current Status and Applications

Message from the Guest Editors

Thermal interface materials play a critical role in enhancing heat dissipation in various applications, including electronics, aerospace, and automotive industries. With the increasing demand for higher performance and the miniaturization of devices, the development of advanced TIMs with improved thermal conductivity, reliability, and durability is essential. Research in this area aims to address challenges related to thermal management and optimize the thermal performance of systems. In this Special Issue, we welcome contributions that explore recent advancements in the design, characterization, and application of thermal interface materials. Topics of interest include, but are not limited to, novel TIM formulations, interface engineering, experimental and computational studies on thermal conductivity, and characterization techniques for TIM properties and performance evaluation. Both theoretical analyses and experimental investigations are encouraged, along with comprehensive review articles that summarize current trends and future directions in the field.

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Editor-in-Chief

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